

## CMS10P10D-HF

**P-Channel**  
**RoHS Device**  
**Halogen Free**



### Features

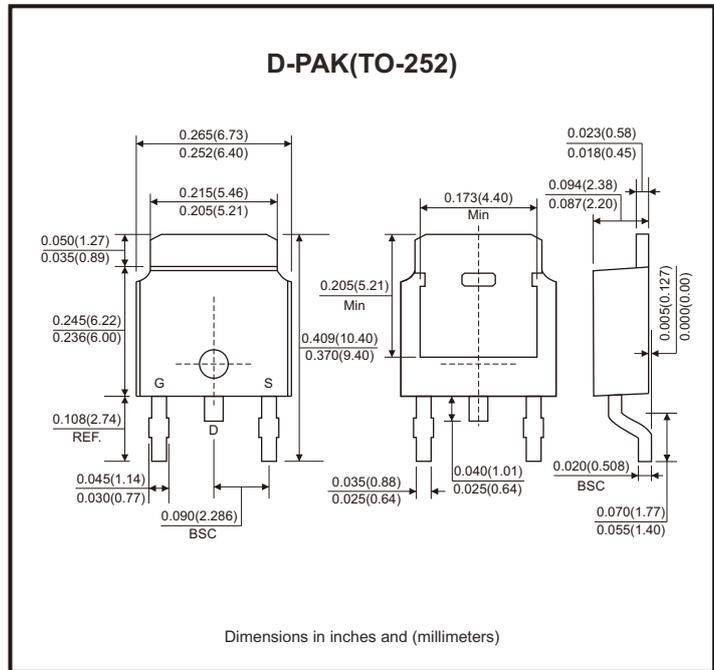
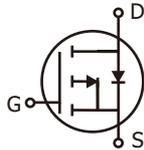
- Low reverse transfer capacitance.
- Improved dv/dt capability.
- 100% EAS guaranteed.
- High switching speed.
- Low gate charge.
- Green device available.

### Mechanical data

- Case: D-PAK/TO-252 standard package, molded plastic.

### Circuit Diagram

- G : Gate
- S : Source
- D : Drain



### Maximum Ratings

Parameter	Conditions	Symbol	Value	Unit
Drain-source voltage		$V_{DS}$	-100	V
Gate-source voltage		$V_{GS}$	±20	V
Continuous drain current (Note 1)	$T_c = 25^\circ\text{C}$	$I_D$	-10	A
	$T_c = 100^\circ\text{C}$	$I_D$	-6	
Pulsed drain current (Note 1, 2)	$T_c = 25^\circ\text{C}$	$I_{DM}$	-40	A
Total power dissipation (Note 4)	$T_c = 25^\circ\text{C}$	$P_D$	54	W
	$T_A = 25^\circ\text{C}$	$P_D$	2	
Single pulse avalanche energy, L=0.1mH (Note 3)		$E_{AS}$	26.4	mJ
Single pulse avalanche current, L=0.1mH (Note 3)		$I_{AS}$	-23	A
Operating junction and storage temperature range		$T_J, T_{STG}$	-55 to +150	°C
Thermal resistance junction-ambient (Note 1)	Steady state	$R_{\theta JA}$	62.5	°C/W
Thermal resistance junction-case (Note 1)	Steady state	$R_{\theta JC}$	2.3	°C/W

## Electrical Characteristics (at $T_j=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS} = 0, I_D = -250\mu\text{A}$	-100			V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1.0	-1.9	-3.0	
Gate-source leakage current	$I_{GSS}$	$V_{GS} = \pm 20\text{V}$			$\pm 100$	nA
Drain-source leakage current	$I_{DSS}$	$V_{DS} = -100\text{V}, V_{GS} = 0$			-1	$\mu\text{A}$
Static drain-source on-resistance (Note 2)	$R_{DS(on)}$	$V_{GS} = -10\text{V}, I_D = -5\text{A}$		170	210	m $\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -3\text{A}$		190	230	
Total gate charge (Note 2)	$Q_g$	$I_D = -5\text{A}, V_{DS} = -80\text{V}, V_{GS} = -10\text{V}$		20		nC
Gate-source charge	$Q_{gs}$			3.5		
Gate-drain ("miller") charge	$Q_{gd}$			4.6		
Turn-on delay time (Note 2)	$t_{d(on)}$	$V_{DD} = -50\text{V}, V_{GS} = -10\text{V}$ $I_D = -5\text{A}, R_G = 25\Omega$		18		nS
Rise time	$t_r$			8		
Turn-off delay time	$t_{d(off)}$			100		
Fall time	$t_f$			30		
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{V}, V_{DS} = -25\text{V}, f = 1\text{MHz}$		1419		pF
Output capacitance	$C_{oss}$			89		
Reverse transfer capacitance	$C_{rss}$			45		
<b>Source-drain diode</b>						
Forward on voltage (Note 2)	$V_{SD}$	$I_S = -1\text{A}, V_{GS} = 0\text{V}$		-0.74	-1.2	V
Continuous source current (Note 1, 6)	$I_S$				-10	A
<b>Guaranteed avalanche characteristics</b>						
Single pulse avalanche energy (Note 5)	EAS	$V_{DD} = -25\text{V}, L = 0.1\text{mH}, I_{AS} = -12\text{A}$	7.2			mJ

- Notes: 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2 oz copper.  
 2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
 3. The EAS data shows max. rating. The test condition is  $V_{DD}=-25\text{V}, V_{GS}=-10\text{V}, L=0.1\text{mH}, I_{AS}=-23\text{A}$ .  
 4. The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature.  
 5. The min. value is 100% EAS tested guarantee.  
 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

## Rating and Characteristic Curves (CMS10P10D-HF)

Fig.1 - Typical Output Characteristics

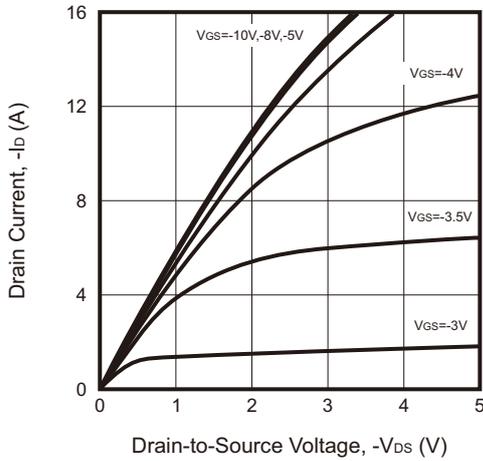


Fig.2 - Transfer Characteristics

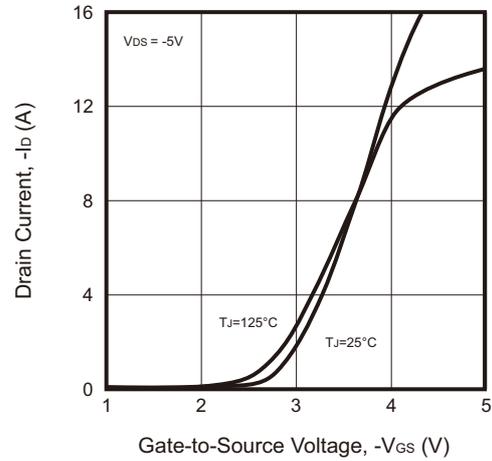


Fig.3 - On-resistance vs. Drain Current

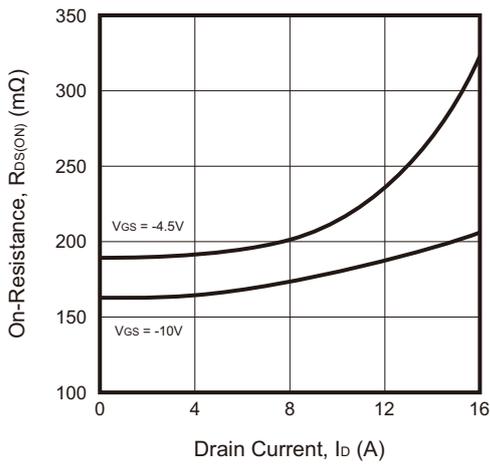


Fig.4 - Normalized  $R_{DS(ON)}$  vs.  $T_J$

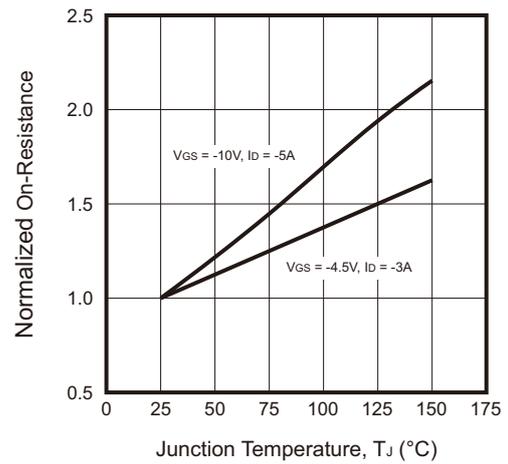


Fig.5 - On-resistance vs. G-S Voltage

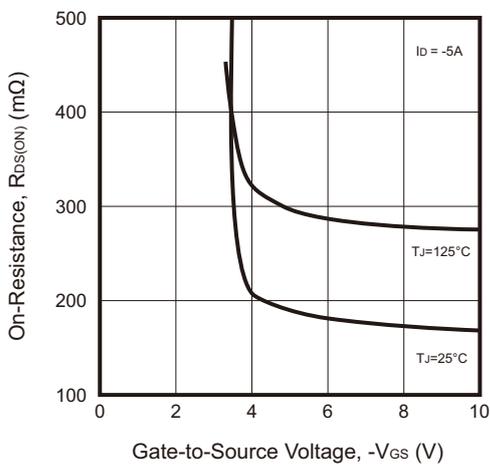
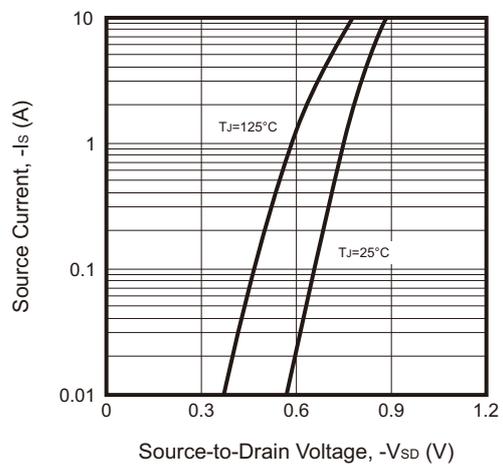


Fig.6 - Forward Characteristics of Reverse



## Rating and Characteristic Curves (CMS10P10D-HF)

Fig.7 - Gate Charge Characteristics

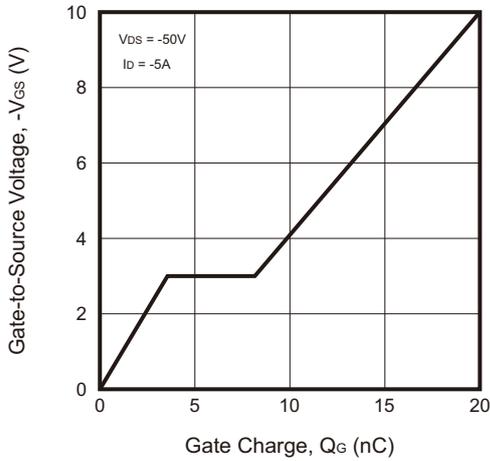


Fig.8 - Capacitance Characteristics

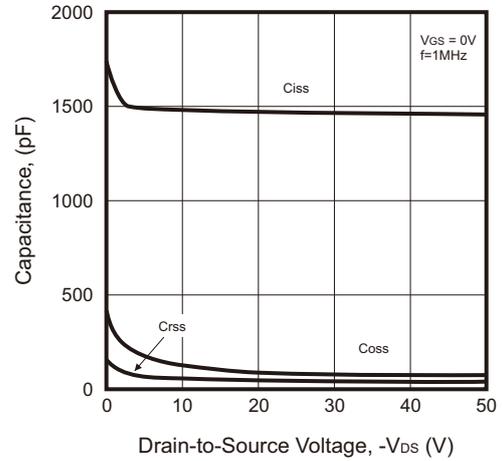


Fig.9 - Safe Operating Area

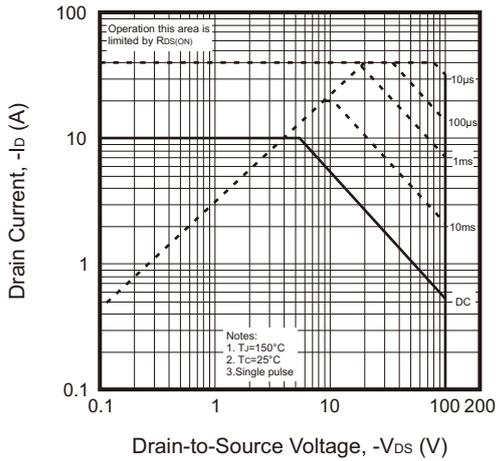
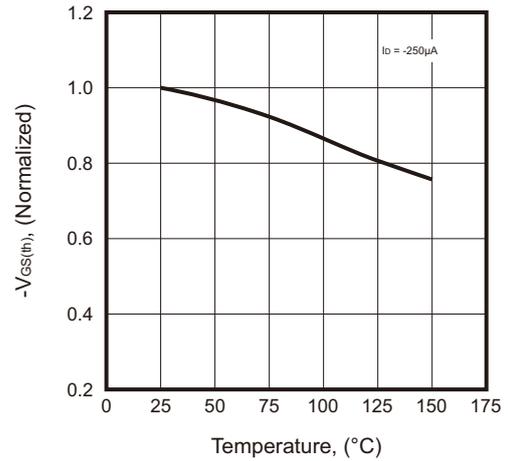
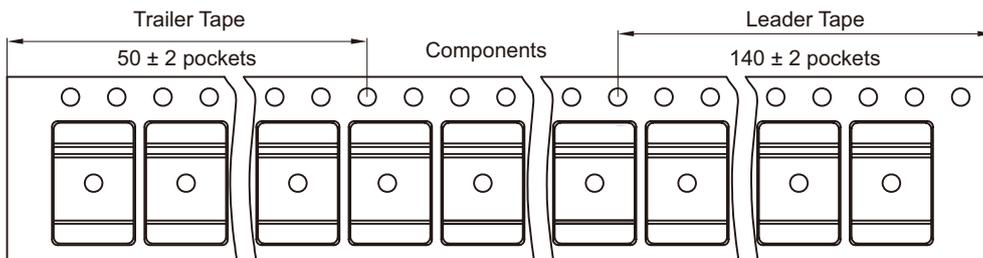
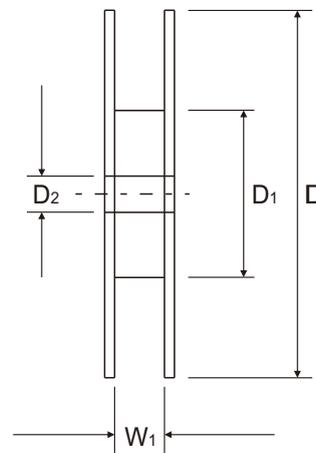
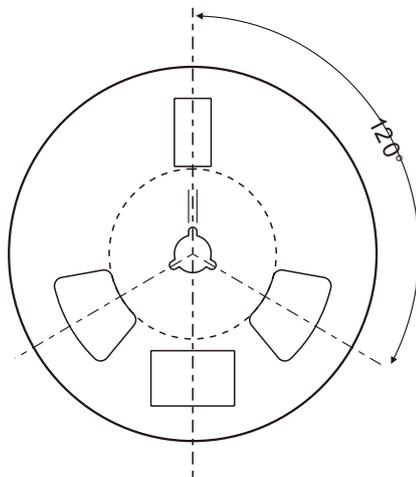
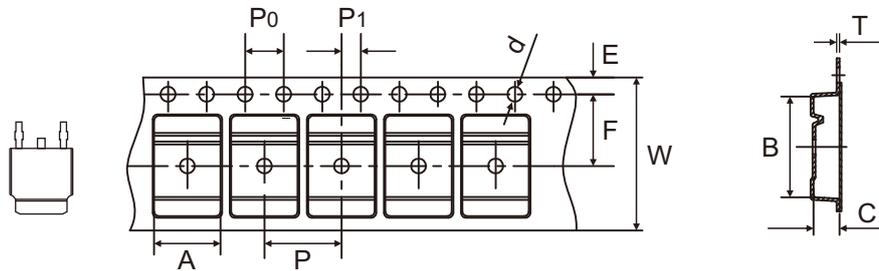


Fig.10 - Normalized  $V_{GS(th)}$  vs. Temperature



Reel Taping Specification



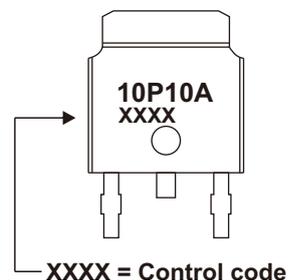
TO-252 (D-PAK)	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	6.90 ± 0.10	10.50 ± 0.10	2.78 ± 0.10	1.50 ± 0.10	330 ± 1.00	100.00 ± 0.50	13.20 ± 0.20
	(inch)	0.272 ± 0.004	0.413 ± 0.004	0.109 ± 0.004	0.059 ± 0.004	12.992 ± 0.039	3.937 ± 0.020	0.520 ± 0.008

TO-252 (D-PAK)	SYMBOL	E	F	P	P0	P1	T	W	W1
	(mm)	1.75 ± 0.10	7.50 ± 0.10	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10	0.25 ± 0.02	16.00 ± 0.10	16.40 ± 0.02
	(inch)	0.069 ± 0.004	0.295 ± 0.004	0.315 ± 0.004	0.157 ± 0.004	0.079 ± 0.004	0.010 ± 0.001	0.630 ± 0.004	0.646 ± 0.01

Company reserves the right to improve product design , functions and reliability without notice. REV:B

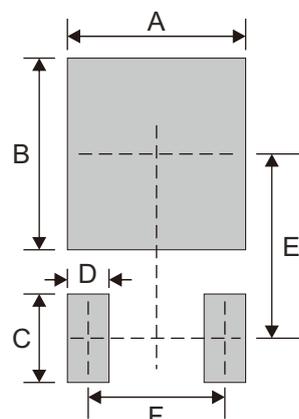
## Marking Code

Part Number	Marking Code
CMS10P10D-HF	10P10A



## Suggested P.C.B. PAD Layout

SIZE	TO-252/D-PAK	
	(mm)	(inch)
A	6.00	0.236
B	6.50	0.256
C	3.00	0.118
D	1.40	0.055
E	6.25	0.246
F	4.60	0.181



Note: 1. The pad layout is for reference purposes only.

## Standard Packaging

Case Type	REEL PACK	
	REEL ( pcs )	Reel Size (inch)
TO-252/D-PAK	2,500	13